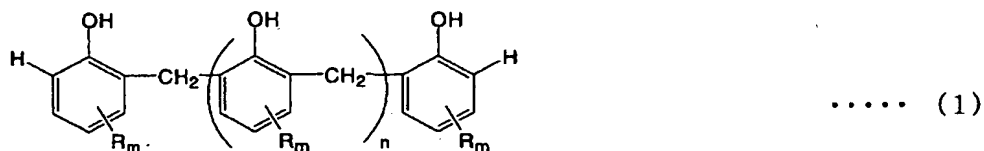


CLAIMS

1. A photosensitive composition characterized by comprising:
from 30 to 90 percent by weight of an epoxy compound (a) having two or more epoxy groups in a molecule;
from 0.1 to 40 percent by weight of a polynuclear phenol compound (b) comprising three to five phenolic aromatic rings, wherein either of the ortho positions of each hydroxyl group is not substituted with any of a methylol group, or an alkyl group or cycloalkyl group having four or more carbon atoms and each of two or more of the phenolic aromatic rings has at least one unsubstituted position ortho to the hydroxyl group; and
from 0.1 to 10 percent by weight of an energy beam-sensitive cationic polymerization initiator (c).

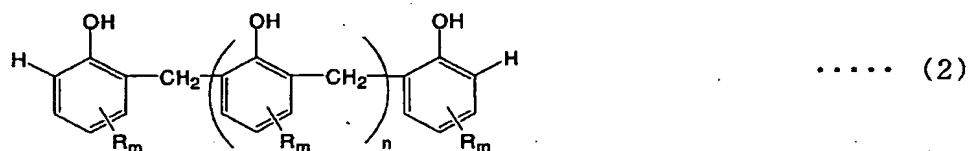
2. The photosensitive composition according to claim 1, further comprising from 1 to 60 percent by weight of a hydroxyl group-containing compound (d) having one or more hydroxyl groups and one or more of at least one of a vinyl ether group and an oxetanyl group in a molecule.
3. The photosensitive composition according to claim 1 or 2, wherein the epoxy groups of the epoxy compound (a) are alicyclic epoxy groups.
4. The photosensitive composition according to any of claims 1 to 3, wherein the polynuclear phenol compound (b) comprises various polynuclear phenol compounds (e) represented by general formula (1):
[Formula 1]



(wherein R denotes a C₁-C₅ alkyl group, a C₅-C₁₀ cycloalkyl group, a C₁-C₅ alkoxy group, a halogen atom, a hydroxyl group, an aryl group or an aralkyl group; all of the plurality of R in the formula each may be the same or different; m is an integer from 0 to 3; and n is an integer from 1 to 3); and

further contains various polynuclear phenol compounds (f) represented by general formula (2):

[Formula 2]

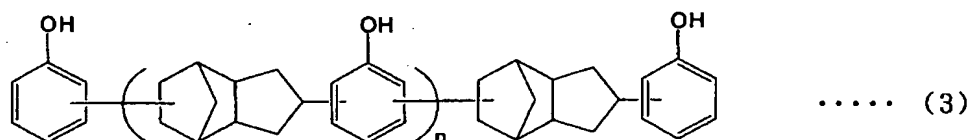


(wherein R denotes a C₁-C₅ alkyl group, a C₅-C₁₀ cycloalkyl group, a C₁-C₅ alkoxy group, a halogen atom, a hydroxyl group, an aryl group or an aralkyl group; all of the plurality of R in the formula each may be the same or different; m is an integer from 0 to 3; and n is an integer of 0 or 4 or more),

the percentage of the polynuclear phenol compounds (e) relative to the total of the polynuclear phenol compounds (e) and (f) being 40 percent by weight or more.

5. The photosensitive composition according to any of claims 1 to 3, wherein the polynuclear phenol compound (b) comprises various polynuclear phenol compounds (g) represented by general formula (3):

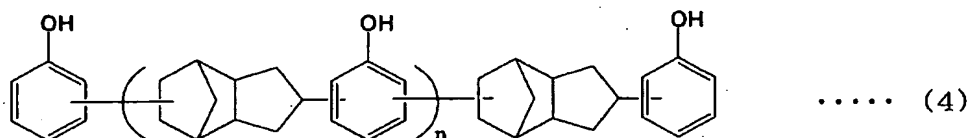
[Formula 3]



(wherein n is an integer from 1 to 3); and

further contains various polynuclear phenol compounds (h) represented by general formula (4):

[Formula 4]



(wherein n is an integer of 0 or 4 or more),

the percentage of the polynuclear phenol compounds (g) relative to the total of the polynuclear phenol compounds (g) and (h) being 40 percent by weight or more.

6. A cured product obtained by irradiating the photosensitive composition according to any of claims 1 to 5 with an active beam and optionally heating the irradiated composition.

7. A photosensitive adhesive comprising the photosensitive composition according to any of claims 1 to 5.
8. A photosensitive coating material comprising the photosensitive composition according to any of claims 1 to 5.
9. A photosensitive ink jet ink comprising the photosensitive composition according to any of claims 1 to 5 and a coloring agent.
10. A cured product obtained by irradiating the photosensitive material according to any of claims 7 to 9 with an active beam and optionally heating the irradiated material.
11. A flat panel display produced by using the photosensitive adhesive according to claim 7 as a sealer.
12. The flat panel display according to claim 11, wherein the flat panel display is an organic electroluminescent display.